





0,50mm HI-SPEED HEADER QTH SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see

www.samtec.co...

Insulator Material:
Crystal

RIE NO. EI I I SM

BIE NO. EI I I SM

BIE NO. EI I I SM Terminal Material: Phosphor Bronze Plating:

Au over 50µ" (1,27µm) Ni Current Rating: Contact: 1.0A @ 30°C Temperature Rise Ground Plane: 7.8A @ 30°C Temperature Rise Operating Temp Range:

-55°C to +125°C Voltage Rating: 125 VAC (5mm Stack Height)
Max Cycles:

Unmating Force (-RT1 option): -RT1 option increases unmating force up to 50% **RoHS Compliant:**

Processing:

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

SMT Lead Coplanarity:

(0,10mm) .004" max (030-060) (0,15mm) .006" max (090-120) Board Stacking:

For applications requiring more than two connectors per board or 4 banks or more, contact ipg@samtec.com

APPLICATION SPECIFIC OPTION

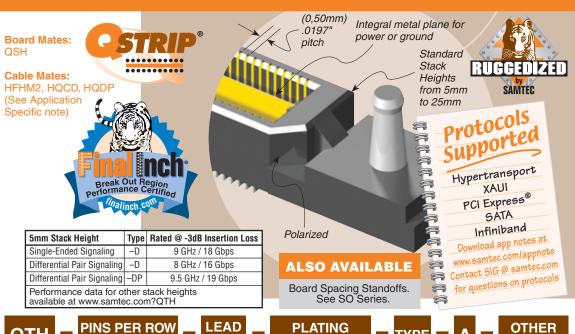
- 14mm, 15mm, 22mm and 30mm stack height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)
- 30µ" (0,76µm) Gold (Specify -H plating for Data Rate cable mating applications.)
- Edge Mount & Guide Posts

Α

• 150 positions per row Call Samtec.

*Note: -C Plating passes 10 year MFG testing

Note: Some lengths, styles and options are non-standard, non-returnable.



-030, -060,–090, –120 (60 total pins per bank = -D)

NO. OF PAIRS

STYLE

LEAD

STYLE

from

chart

–020, –040, -060, -080 (20 pairs per bank = -D-DP)

-01 & -02

-D = (No. of Pins per Row/30)x (20,00) .7875 -DP = (No. of Pairs per Row/20) x (20,00) .7875 (20.00) .7875 (7,11) .280 (0,20) 008

= 10µ" (0,25µm) Gold on Signal Pins and Ground Plane, Matte Tin on tails

OPTION

= Gold Flash on Signal Pins and Ground Plane, Matte Tin on tails

= Electro-Polished Selective 50μ" (1,27μm) min Au over 150μ" (3,81μm) Ni on Signal Pins in contact area, 10μ" (0,25μm) min Au over 50μ" (1,27μm) Ni on Ground Plane in contact area, Matte Tin over 50μ" (1,27μm) min Ni on all solder tails

.030

(0.89)

035

DIA

-01

(3,30) .130

062

DIA

_RT1

.062

-D = Single-Ended –D–DP Differential Pair (-01 only)

-K = (7,00mm) .275" DIA Polyimide film Pick & Place Pad

OPTION

–TR = Tape & Reel -090 positions maximum)

-RT1 = Retention Option (–01 Lead Style only & 090 positions maximum)

QTH LEAD STYLE	Α	HEIGHT WITH QSH
-01	(4,27) .168	(5,00) .198
-02	(7,26) .286	(8,00) .316
-03	(10,27) .404	(11,00) .433
-04	(15,25) .600	(16,00) .630
-05	(18,24) .718	(19,00) .748
-07	(24,24) .954	(25,00) .984

Due to technical progress, all designs, specifications and components are subject to change without notice.

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-03 thru -07